



Integrated Device Technology, Inc.

6024 Silver Creek Valley Road
San Jose, CA 95138 USA

Manufacturing Bulletin

Date: November 27, 2012

Subject: IDT Temp Sensor Product Top Mark

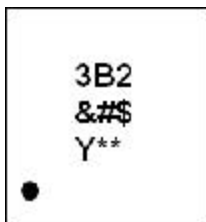
The purpose of this bulletin is to notify our customers that IDT is implementing a top mark change for the following device types effective 1st January 2013.

AFFECTED PART#	AFFECTED PART#
TSE2002GB2A1NCG	TSE2002GB2A1NRG
TSE2002GB2A1NCG8	TSE2002GB2A1NRG8
TS3000GB2A1NCG	TS3000GB2A1NRG
TS3000GB2A1NCG8	TS3000GB2A1NRG8
TS3001GB2A0NCG	TS3001GB2A0NRG
TS3001GB2A0NCG	TS3001GB2A0NRG

The new format provides a better coverage for lot traceability.

Presently these devices are marked as follows:

Existing Top Mark Format



- Line 1: PART NUMBER
- Line 2: & - DEVICE STEPPING, A = STEP
- PACKAGE CODE, C = NCG; R = NRG
\$ - ASSEMBLY LOCATION, W = Carsem
- Line 3: Y - YEAR, 2 = 2012
** - SEQUENTIAL LETTERS FROM AA TO ZZ
(for lot traceability)



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The new top mark format is as follows:

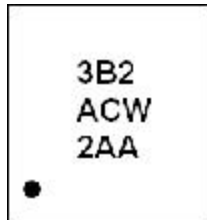
New Top Mark Format



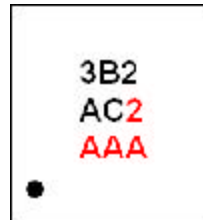
- Line 1: PART NUMBER
Line 2: & - DEVICE STEPPING, A = STEP
- PACKAGE CODE, C = NCG; R = NRG
Y - YEAR, 2 = 2012
Line 3: ***** - SEQUENTIAL LETTERS FROM
AAA TO ZZZ
(for lot traceability)**

Example of Top mark for TSE2002GB2A1NCG

Existing Top Mark Format



New Top Mark Format



Please contact your sales representative if you have any additional questions or concerns.

Yours sincerely,

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